

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 04-093092

(43)Date of publication of application : 25.03.1992

(51)Int.Cl.

H05K 1/02

(21)Application number : 02-209928

(71)Applicant : NEC CORP

(22)Date of filing : 08.08.1990

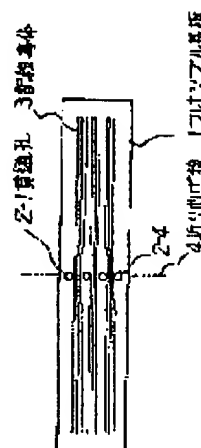
(72)Inventor : MIYAUCHI HIDEO

(54) FLEXIBLE CIRCUIT BOARD

(57)Abstract:

PURPOSE: To bend a flexible board after components are placed due to easy bending process, to reduce roundness at a bending position and to reduce entire thickness by providing through holes on a bending line of the board.

CONSTITUTION: Through holes 2-1-2-4 each having 2.0mm of diameter are provided at a pitch of 3.5mm along a bending line 4 of a flexible board 1 (insulating resin film having about 200 μ m of thickness), and wiring conductors 3 of copper foil are disposed between the holes. It is easy to bend along the line, and can be bent after components are placed. The entire thickness after bending is about 5mm in prior art example, but reduced to about 2mm in this embodiment.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

BEST AVAILABLE COPY

Copyright (C); 1998,2003 Japan Patent Office

BEST AVAILABLE COPY